

09198031

		Class	Subj.
--	--	-------	-------

ISSUE CLASSIFIC.

FILED UNDER 35 U.S.C. 371

U.S. UTILITY Patent Application

O.I.P.E.	PATENT DATE
SCANNED <u>AD4</u> Q.A. <u>SB</u>	

APPLICATION NO. 09/980317	CONT/PRIOR D F	CLASS 257	SUBCLASS 734	ART UNIT 2611 2622	EXAMINER SIVARD
------------------------------	-------------------	--------------	-----------------	--	--------------------

PLICANTS Jozef Puymbroeck

E Substrate with at least two metallized polymer bumps for soldered connection to wiring

PTO-2040
12/89

ISSUING CLASSIFICATION

Continued on Issue Slip Inside File Jacket

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.				NOTICE OF ALLOWANCE MAILED	
	(Assistant Examiner)	(Date)			
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____				ISSUE FEE	
	(Primary Examiner)	(Date)		Amount Due	Date Paid
<input type="checkbox"/> The terminal ____ months of this patent have been disclaimed.				ISSUE BATCH NUMBER	
	(Legal Instruments Examiner)	(Date)			

WARNING:

The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.

Form PTO-438A
(Rev. 6/99)

FILED WITH: DISK (CRF) FICHE CD-ROM
(Attached in pocket on right inside flap)

BEST AVAILABLE COPY

(FACE)